



Material Content Data Sheet



Sales Product Name		ESD200-B1-CSP0201 E6327		Issued		29. August 2013		
MA#		MA001091308						
Package		SG-WLL-2-1		Weight*		0.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.063	94.55	94.55	945447	945447
pad	inorganic material	phosphorus	7723-14-0	0.000	0.09		857	
	noble metal	gold	7440-57-5	0.000	0.09		902	
passivation	noble metal	palladium	7440-05-3	0.000	0.56		5621	
	non noble metal	nickel	7440-02-0	0.003	4.13	4.87	41268	48648
	inorganic material	SiO2	60676-86-0	0.000	0.07		691	
metallization	inorganic material	Si3N4	-	0.000	0.12	0.19	1232	1923
	non noble metal	copper	7440-50-8	0.000	0.00		45	
	inorganic material	silicon	7440-21-3	0.000	0.00		15	
	non noble metal	aluminium	7429-90-5	0.000	0.39	0.39	3922	3982
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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